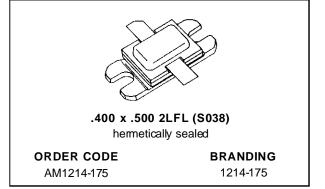


AM1214-175

RF & MICROWAVE TRANSISTORS L-BAND RADAR APPLICATIONS

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- 3:1 VSWR CAPABILITY
- LOW THERMAL RESISTANCE
- INPUT/OUTPUT MATCHING
- OVERLAY GEOMETRY
- METAL/CERAMIC HERMETIC PACKAGE
- POUT = 160 W MIN. WITH 7.3 dB GAIN

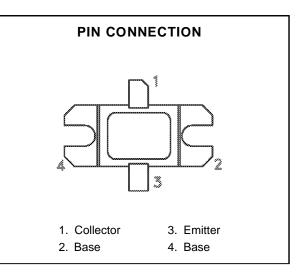


DESCRIPTION

The AM1214-175 device is a high power Class C transistor specifically designed for L-Band radar pulsed output and driver applications.

This device is capable of operation over a wide range of pulse widths, duty cycles and temperatures and is capable of withstanding 3:1 output VSWR at rated RF conditions. Low RF thermal resistance and computerized automatic wire bonding techniques ensure high reliability and product consistency.

The AM1214-175 is supplied in the BIGPAC[™] Hermetic Metal/Ceramic package with internal Input/Output matching structures.



Symbol	Parameter	Value	Unit	
PDISS	Power Dissipation [*] $(T_C \le 100^{\circ}C)$	330	W	
Ic	Device Current*	14	А	
Vcc	Collector-Supply Voltage*	45	V	
TJ	Junction Temperature (Pulsed RF Operation)	250	°C	
T _{STG}	Storage Temperature	– 65 to +200	°C	

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)

THERMAL DATA

RTH(j-c)Junction-Case Thermal Resistance*0.45°C/W

*Applies only to rated RF amplifier operation

ELECTRICAL SPECIFICATIONS ($T_{case} = 25^{\circ}C$)

STATIC

Symbol	Test Conditions		Value			Unit
	Test conditions		Min.	Тур.	Max.	Unit
BV _{CBO}	$I_{C} = 60 \text{mA}$ $I_{E} = 0 \text{mA}$		65		—	V
BVEBO	$I_E = 10 \text{mA}$ $I_C = 0 \text{mA}$		3.5	_	_	V
BVCES	IC = 100mA		65	-	_	V
ICES	$V_{CE} = 40V$		_	_	25	mA
h _{FE}	$V_{CE} = 5V$ $I_C = 5A$		15	_	150	

DYNAMIC

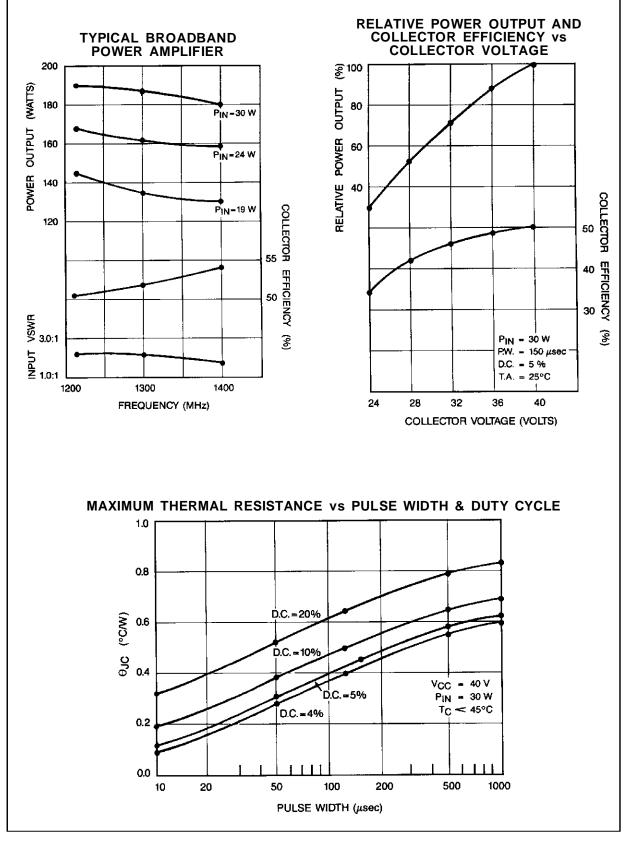
Symbol	Test Conditions		Value			Unit	
Symbol			Min.	Тур.	Max.	Unit	
Роит	f = 1215 — 1400MHz	$P_{\text{IN}}=30W$	$V_{CC} = 40V$	160	180	—	W
ηc	f = 1215 — 1400MHz	$P_{IN} = 30W$	$V_{CC} = 40V$	45	50	—	%
GP	f = 1215 — 1400MHz	$P_{IN} = 30W$	$V_{CC} = 40V$	7.3	7.8	_	dB

Note: Pulse Width = 150μ S

Duty Cycle = 5%



TYPICAL PERFORMANCE

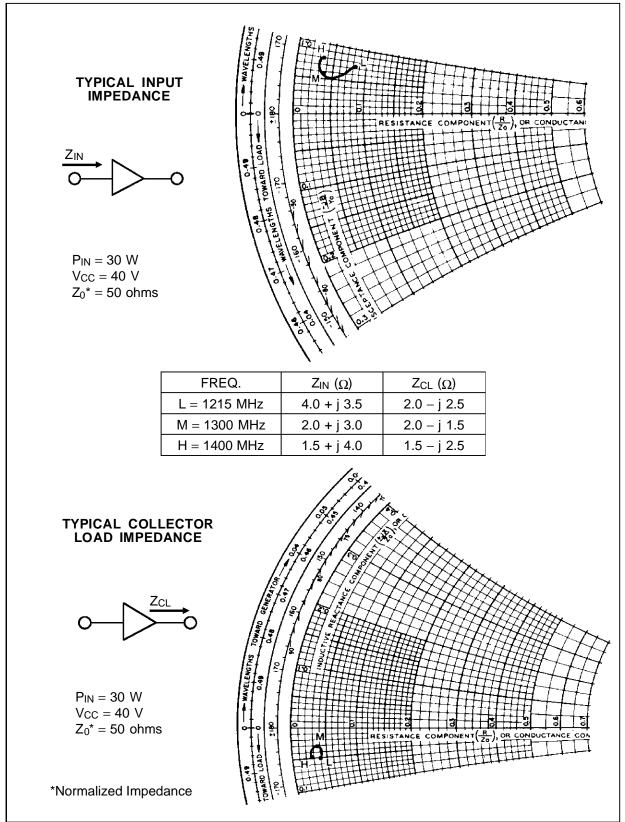


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MICROELECTRONICS

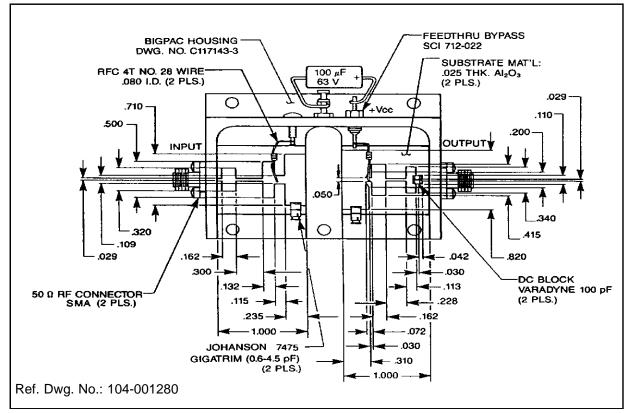
47/.

IMPEDANCE DATA

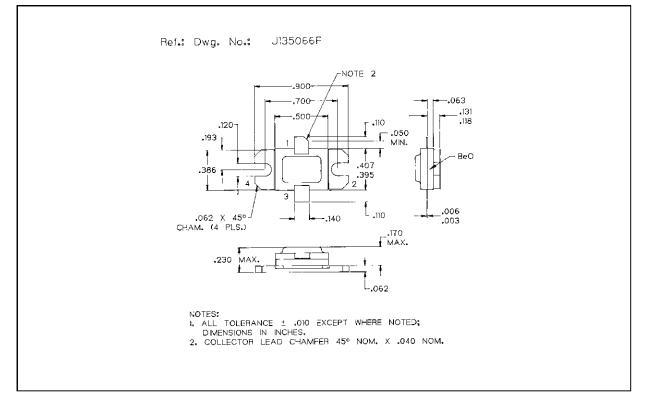




TEST CIRCUIT



PACKAGE MECHANICAL DATA





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